

removing a portion of said bonding material so as to leave said bonding material recessed below the surface of said support member;

coating said bonding material and the projecting portion of said optical element with a layer of material which is not prone to emitting undesirable components and which limits passage of any undesirable components emitted by said bonding material; and

removing that portion of said layer of material which coats said projecting portion of said optical element while leaving that portion of said layer of material which coats said bonding material intact.

17 (Previously Amended): The process of claim 15 wherein said step of removing that portion of said layer of material which coats said projecting portion of said optical element also removes said projecting portion of said optical element to leave said optical element flush with the surface of said support member.

18(original): The process of claim 15 wherein said bonding material is epoxy resin.

19(original): The process of claim 15 wherein said sealing material is metal.

20(original): The process of claim 15 wherein said optical element is an optical fiber.

22(original): A process of sealing an optical fiber bonded to a support member with epoxy resin bonding material comprising the steps of:

placing an optical fiber through an opening in the support member which has a cross-section which is greater than the cross-section of the optical fiber such that there is a space between the optical fiber and the support member, and the optical fiber projects beyond a surface of said support member;

filling said space between said optical fiber and said support member with an epoxy resin bonding material which is prone to emit undesirable components;

removing a portion of said epoxy resin bonding material so as to leave said bonding material recessed below the surface of said support member;

coating said epoxy resin bonding material and the projecting portion of said optical fiber with a layer of material which layer limits passage of any undesirable components emitted by said epoxy resin bonding material; and

removing that portion of said layer of material which coats said projecting portion of said optical fiber while leaving that portion of said layer of material which coats said bonding material intact and also removing said projecting portion of said optical element to leave said optical element flush with the surface of said support member.

32(original): A process of sealing an element bonded to a support member using epoxy resin bonding material comprising the steps of:

placing an element through an opening in the support member which has a cross-section which is greater than the cross-section of the element such that there is a space between the

element and said support member, and the element projects beyond a surface of said support member;

filling said space between said element and said support member with an epoxy resin bonding material which is prone to emit undesirable components;

removing a portion of said epoxy resin bonding material so as to leave said bonding material recessed below the surface of said support member;

coating said epoxy resin bonding material and the projecting portion of said element with a layer of a sealing material which is not prone to emitting undesirable components and which limits passage of any undesirable components emitted by said epoxy resin bonding material; and

removing that portion of said layer of sealing material which coats said projecting portion of said element while leaving that portion of said layer of sealing material which coats said bonding material essentially intact and also removing said projecting portion of said element to leave said element flush with the surface of said support member.

REMARKS

Claims 15, 17, 18, 19, 20, 22, and 32 remain in the application and claims 1-4, 10-13, and 23-29 have been cancelled in this response and claims 5-9, 14, 16, 21, 30, and 31 were previously cancelled in a preliminary amendment.

The Examiner has rejected claims 1-4, 10-13, and 23-29 and has allowed claims 15, 17, 18, 19, 20, 22, and 32.